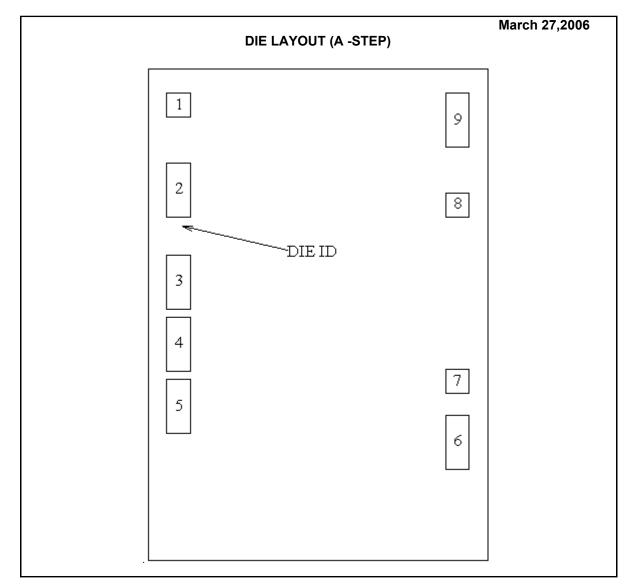


LM2660 MDC MWC SWITCHED CAPACITOR VOLTAGE CONVERTER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die Identification	LM2660A	Bond Pad Opening Size (min)	102μm x 102μm	
Die Step	A	Bond Pad Metalization	Al_1.5%Si 0.5%Cu	
Physical Attributes		Passivation	PECVDOX+NITIRDE	
Wafer Diameter	200mm	Back Side Metal	Bare Back	
Die Size (Drawn)	1473.2μm x 2133.6μm 58.0mils x 84.0mils	Back Side Connection	Floating	
Thickness	330µm Nominal			
Min Pitch	263µm Nominal			

Special Assembly Requirements: Note: Actual die size is rounded to the nearest micron.



DPBU Die Datasheet

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	Die Bond Pad Coordinate Locations (A -Step)								
(Re	(Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used								
SIGN	IAL PAD#	X/Y CO	DORDINATE	S F	PAD SI	ZE			
NAM	E NUMBER	ч χ	Y	Х		<u>Y</u>			
FC	1	-604	911	102	х	102			
CAP	+ 2	-604	544	102	Х	234			
GND	3	-604	144	102	х	234			
GND	4	-604	-125	102	х	234			
CAP	. 5	-604	-397	102	х	234			
OUT	6	604	-552	102	х	234			
LV	7	604	-288	102	х	102			
OSC	8	604	478	102	х	102			
V+	9	604	845	102	х	234			



DPBU Die Datasheet

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